



(1.00 mm) .0394"

MLE-150-01-G-DV

MLE-120-01-G-DV

CLM-111-02-L-D

CLM-126-02-F-D

CLM, MLE SERIES

RUGGED RELIABLE MICRO SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM or www.samtec.com?MLE

Insulator Material:

Black LCP

Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

Plating:

CLM: Au or Sn over 50 μ" (1.27 μm) Ni

MLE: Au over 10 μ" (0.25 μm) Ni

Current Rating (CLM/FTM):

2.8 A per pin

(2 pins powered)

Current Rating (MLE/FTM):

2.9 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Max Cycles:

CLM: 100 with 10 μ" (0.25 μm) Au

Voltage Rating:

MLE: 310 VAC

Insertion Depth:

CLM: Top Entry = (1.40 mm)

.055" min., Bottom Entry =

(2.41 mm) .095" min.

(Add board thickness for correct post OAL)

MLE: (1.63 mm) .064" to

(3.18 mm) .125" with

(0.38 mm) .015" wiper,

pass-through, or

(2.44 mm) .096" minimum

for bottom entry

Normal Force:

CLM: 40 grams (0.39 N) average

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-50)*

*(.004" stencil solution

may be available; contact

IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note:
Some lengths, styles and options are non-standard, non-returnable.

CLM

1

NO. PINS PER ROW

02

PLATING OPTION

D

OPTIONS

Mates with:

FTM, FTMH, MW

02 thru 50

—F
= Gold flash on contact,
Matte Tin on tail

—L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

—BE
= Bottom Entry
(Required for bottom entry)

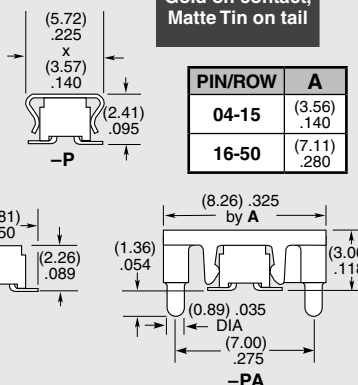
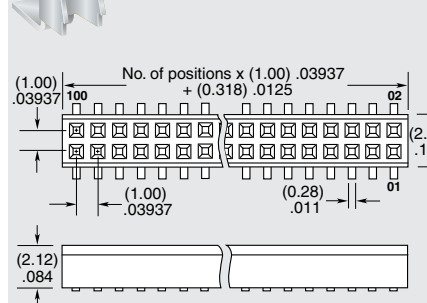
—K
= (3.50 mm) .138" DIA
Polyimide film Pick & Place Pad
(7 positions minimum)

—P
= Pick & Place Pad
(7 positions minimum)

—PA
= Pick & Place Pad with
integral Alignment Pin

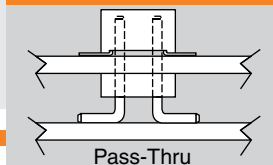
—TR
= Tape & Reel Packaging

—FR
= Full Reel Tape & Reel
(must order max. quantity per
reel; contact Samtec for
quantity breaks)



PIN/ROW	A
04-15	(3.56) .140
16-50	(7.11) .280

APPLICATION



ALSO AVAILABLE (MOQ Required)

- Alignment pin
- Other Gold plating options

MLE

1

NO. PINS PER ROW

01

PLATING OPTION

DV

OPTIONS

Mates with:

FTM, FTMH, MW

02 thru 50

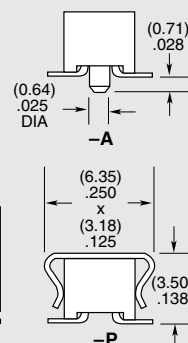
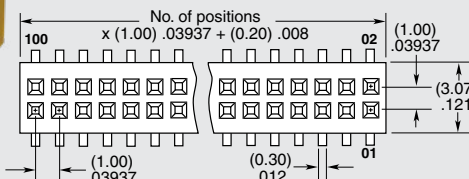
—G
= 10 μ" (0.25 μm)
Gold

—A
= Alignment Pin
(3 positions minimum)
Metal or plastic at Samtec
discretion

—K
= (4.00 mm) .1575" DIA
Polyimide film Pick & Place Pad
(5 positions minimum)

—P
= Metal Pick & Place Pad
(5 positions minimum)

—TR
= Tape & Reel Packaging



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Components must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.